DISCOUNT REGISTRATION DEADLINE:
SEPTEMBER 27, 2023

November 12-15, 2023

Omni William Penn Hotel, Pittsburgh, Pennsylvania, USA
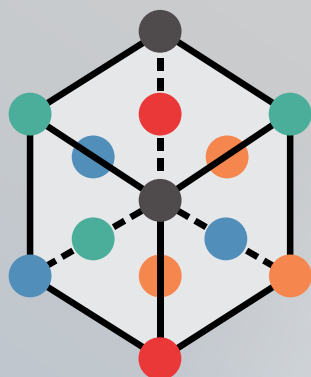
3rd WORLD CONGRESS ON
HIGH ENTROPY ALLOYS
HEA 2023

www.tms.org/HEA2023

The 3rd World Congress on High Entropy Alloys (HEA 2023) is a cross-disciplinary technical forum designed to share the latest research advances in single-phase and multi-phase metallic, intermetallic, and ceramic high entropy materials for functional or structural applications. HEA 2023 will feature highly focused technical talks on topics that include, but are not limited to, fundamental theory of alloy design, computational modeling and simulation, properties, processing, and applications of high entropy alloys.

HEA 2023 will feature:

- Networking opportunities that offer attendees a chance to informally discuss and make valuable professional connections
- A robust series of presentations, including:
  - Plenary Speakers: **Zhaoping Lu**, University of Science and Technology Beijing; **Evan Ma**, Xi'an Jiaotong University; **Daniel B. Miracle**, Air Force Research Laboratory; and **Mitra Taheri**, Johns Hopkins University
  - Invited Presentations from 12 Experts in the Field
- An Optional Tour of the Carrie Blast Furnace Historical Site

Congress participants are encouraged to submit their work to the journal *Metallurgical and Materials Transactions A*, which will be publishing a topical collection dedicated to HEA 2023 in the place of a traditional conference proceedings publication. Only submissions from HEA 2023 attendees will be considered. Submissions will go through the journal's standard peer review process and there is no guarantee of acceptance. Submissions are due January 31, 2024.

Register today and book your accommodations at
www.tms.org/HEA2023

Organizers:

Chair:
Andrew Detor,
DARPA, USA

Programming Chair:
Amy Clarke,
Colorado School of Mines, USA

Organizing Team:
Martin Heilmaier,
Karlsruhe Institute of Technology, Germany

Keith Knipling,
Naval Research Laboratory, USA

Elizabeth Opila,
University of Virginia, USA

Oleg N. Senkov,
MRL Materials Resources LLC and Air Force Research Laboratory, USA

C. Cem Tasan,
Massachusetts Institute of Technology, USA

Mike Titus,
Purdue University, USA